

Advanced Product / Process Change Notice

Date: 06/22/2017

No.: Z200-APCN-AM201705-01-Q

Change Title: To change LOC (Lead On Chip) to Non LOC (Lead On Chip) type of TSOPII-54 & 66 package. Change item : ☐ Design ☐ Raw Material ☐ Wafer FAB ☐ Assembly ☐ Packing ☐ Testing ☐ Others Affected Product(s): Please refer to Table 1 in details. Description of Change(s): To change LOC (Lead On Chip) to Non LOC (Lead On Chip) type of TSOPII-54 & 66 package Reason for Change(s): Hitachi announced the EOL of LOC tape, model HM-122U-FE100, which impacted Winbond's TSOP II package type parts. Thus Winbond needs to change to the Hitachi non LOC tape, model epoxy EN-4900. Impact of Change(s): (positive & negative) Form: No Change Fit: No Change Function: No Concern (Please refer to attachment I) Reliability: On-going Hazardous Substances: No Concern (Please refer to attachment II) Qualification Plan/ Results: Package qualification is in progress and expected come out in Jan/2018. Implementation Plan: ■ Date Code: onward □ Lot No: onward ☑ Proposed first ship date: 02/28/2018 Approval: (QA Originator: (QA) Approval: (QRA yt chang Hyhuang Dept. Manager) Director) Name: Betty Huang TEL:886-3-5678168 (ext.86549) FAX: 886-3-5796124 **Contact for Questions** Address: # 539, Sec. 2, Wenxing Rd., Jhubei City, Hsinchu County 302, Taiwan & Concerns E-mail: Hyhuang8@winbond.com



Customer Comments:

Note: Please sign this notice, and return to Winbond contact within **30** days. If no response is received within **30** days, this Change Request will be assumed to meet your approval.

■ Approval	■ Disapproval	□ Conditional Approval :
Comment:		
Date:		
		-
Dept. name:		
Person in charge:		



Table 1. The affected part no are list below.

W9425G6JH-4	W9425G6JH-5H	W9825C6JH-6K	W9825G6JH-6K	W9825G6JH75L
W9425G6JH-4D	W9425G6JH-5I	W9825G6JH-6	W9825G6JH-6P	W9825G6JH75P
W9425G6JH-4P	W9825C6JH-6A	W9825G6JH-6A	W9825G6JH6PI	W9825G6PH-6
W9425G6JH-5	W9825C6JH-6I	W9825G6JH-6I	W9825G6JH-75	

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Table No.: 1110-0001-08-A